

1762

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PATENT
Attorney Docket No.: 16301-040300
Client Ref. No.: AMAT/4142/PDD/LOW K/JW



On 7-1-02

TOWNSEND and TOWNSEND and CREW LLP

By: Kula Shaffer

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#13/C
Jula
8/6/02

In re application of:

Hari Ponnekanti et al.

Application No.: 09/502,126

Filed: February 10, 2000

For: A PROCESS AND AN
INTEGRATED TOOL FOR LOW K
DIELECTRIC DEPOSITION
INCLUDING A PECVD CAPPING
MODULE

Examiner: Bret Chen

Art Unit: 1762

RESPONSE TO NOTICE OF NON-
COMPLIANT AMENDMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

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Sir:

In response to the Notice of Non-Compliant Amendment mailed June 4, 2002, applicants submit herewith the amended paragraphs objected to by the Examiner.

IN THE SPECIFICATION:

Please replace the paragraphs beginning at page 7, line 19, through page 8, line 24, with the following rewritten paragraphs:

-- Figure 1 is a top schematic view of a radial cluster tool for batch processing of semiconductor substrates;

Figure 2A is a top schematic view of one embodiment of an apparatus containing a capping module and high pressure deposition module of the present invention;

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